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APPARATUS AND METHOD FOR SEMICONDUCTOR WAFER EDGE INSPECTION

Abstract of the Disclosure

Apparatus and method for the inspection of the edges of multiple semiconductor wafers at the same time. The wafers are held in a cassette and a columnar beam of light is projected tangentially to an upper edge portion of the wafers. Visual detection of back scattering of light from the edge of any of the wafers reveals the edge defect. Rotation of the wafers using the apparatus permits the entire circumference of the wafers to be inspected. The apparatus holds the wafers in such a way as to protect their polished surfaces during the inspection process.

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